

IN THE UNITED STATES PATENT & TRADEMARK OFFICEIN RE APPLICATION OF :
:

ROBERT PHILIPPE : ATTN: APPLICATION DIVISION

SERIAL NO: NEW U.S. PCT APPLN :
(Based on PCT/FR00/02065)FILED: HEREWITH : EXAMINER:
:FOR: METHOD OF FABRICATING :
THROUGH-CONNECTIONS A
SUBSTRATE, AND SUBSTRATE
EQUIPPED WITH SUCH CONNECTIONSPRELIMINARY AMENDMENTASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to a first examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel Claims 1-10 without prejudice.

Please add new Claims 11-20 as follows:

11. (New) A method of fabricating conducting through-connections between a front face and a rear face of a substrate, comprising:

A1
Cop hollowing into the substrate, from the rear-face side, cavities having a depth and a cross-section which are defined so as to delimit, by these cavities, studs of defined cross-section configured to provide for electrical conduction between the front and rear faces;